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Planning

NMIS Power Electronics Advanced Packaging Semiconductor Facility, dedicated die bonding, wire bonding, and encapsulation equipment.

University of Strathclyde

F01: Prior information notice
Prior information only
Notice identifier: 2023/S 000-024848
Procurement identifier (OCID): ocds-h6vhtk-03f66f
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Section I: Contracting authority

I.1) Name and addresses

University of Strathclyde

McCance Building, 16 Richmond Street

Glasgow

G1 1QE

Email

jemma.wylie@strath.ac.uk

Telephone

+44 7811592949

Country

United Kingdom

NUTS code

UKM82 - Glasgow City

Internet address(es)

Main address

http://www.strath.ac.uk/

Buyer's address

https://www.publiccontractsscotland.gov.uk/search/Search_AuthProfile.aspx?ID=AA00113

I.2) Information about joint procurement

The contract is awarded by a central purchasing body

I.3) Communication

Additional information can be obtained from the above-mentioned address

I.4) Type of the contracting authority

Body governed by public law

I.5) Main activity

Education

Section II: Object

II.1) Scope of the procurement

II.1.1) Title

NMIS Power Electronics Advanced Packaging Semiconductor Facility, dedicated die bonding, wire bonding, and encapsulation equipment.

Reference number

UOS-29683-2023

II.1.2) Main CPV code

- 31712330 - Semiconductors

II.1.3) Type of contract

Supplies

II.1.4) Short description

NMIS is in the process of expanding its manufacturing capability into the semiconductor advanced packaging area with specific focus on power electronic semiconductors. To support this expansion, NMIS intends to procure equipment that is flexible to support a wide variety of power electronic semiconductor designs and packaging requirements. The initial focus will be procuring equipment to support die bonding, wire bonding and encapsulation and associated ancillaries required.

II.1.5) Estimated total value

Value excluding VAT: £1,900,000

II.1.6) Information about lots

This contract is divided into lots: No

II.2) Description

II.2.2) Additional CPV code(s)

- 31710000 - Electronic equipment

II.2.3) Place of performance

NUTS codes

- UKM82 - Glasgow City

II.2.4) Description of the procurement

NMIS is in the process of expanding its manufacturing capability into the semiconductor advanced packaging area with specific focus on power electronic semiconductors. To support this expansion, NMIS intends to procure equipment that is able to support a wide variety of power electronic semiconductor designs and packaging requirements.

The concept design for the facility includes provision of equipment that is sufficiently flexible to support a wide variety of power electronic semiconductor designs and packaging requirements. The items procured will enable NMIS to set up a research facility for developing and scaling-up advanced packaging capabilities for power electronic semiconductors. The overall facility will have capability to prepare, dice/cut, bond, interconnect, package and test semiconductor products that are part of the power electronics sector. These stages will be carried out across dedicated research and development cells.

The initial focus will be procuring equipment as a 3 cell solution as Cell 6, Cell 7 and Cell 8 of a production line to support die bonding, wire bonding and encapsulation and associated ancillaries required. The University is seeking a supplier to supply, deliver and commission all of the equipment to provide the following overall capability:

Cell 6: Die Attach

- Automatic die bonding

- Vacuum oven curing

- Plasma cleaning

Cell 7: Interconnection

- Multi-head wire bonding

- Ultrasonic bonding

Cell 8: Encapsulation

- Overmoulding

- Dam and fill encapsulation

- Oven curing

II.3) Estimated date of publication of contract notice

2 October 2023

Section IV. Procedure

IV.1) Description

IV.1.8) Information about the Government Procurement Agreement (GPA)

The procurement is covered by the Government Procurement Agreement: Yes

Section VI. Complementary information

VI.3) Additional information

NOTE: To register your interest in this notice and obtain any additional information please visit the Public Contracts Scotland Web Site at https://www.publiccontractsscotland.gov.uk/Search/Search_Switch.aspx?ID=742450.

(SC Ref:742450)